



### 半导体行业数字化、智能化的挑战与解决方案

西門子工業軟體全球半導體行業發展執行總監 申云勇 David Shen

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#### 最近的电子与半导体市场生态系统的驱动因子

#### 智能接口和 VR / AR 持续增长

- Augmented Reality to reach \$120Bby 2020 (driven by hardware sales).
- Nintendo's market value went up \$9B in 5 days because of AR.



#### 将IoT理念设计运用到新产品中

- Smart TV's include Smart Home hubs for connected products
- Amazon has over 1000 people working on Echo design team to add connected device capabilities



#### IoT是未来3 - 5年主要驱动市场的发展力量

- 1/6 consumers currently own and use wearable tech.
- IoT: Over 50 billion internetconnected devices will exist worldwide by 2020.



#### 汽车电子和成像电子产品是一个崭新的领域

- Electric vehicles Tesla Model 3 received 400,000 orders in 2 weeks
- US Government opened up \$4.5B in loan guarantees to boost electric vehicle infrastructure





缩短技术创新采用的时间 Shorter technology Innovation Adoption Time Becomes Shorter.



更难实现跨越供应链的协同合作 More difficult to enable collaboration across and through the Supply Chain.



无法实现零缺陷将导致收入/市场 份额的损失

Inability to achieve zero defect will cause loss of revenue/market share.



提供给制造环境需要的闭环、智 能集成

Manufacturing environment needs to be closed loop, intelligent and integrated.



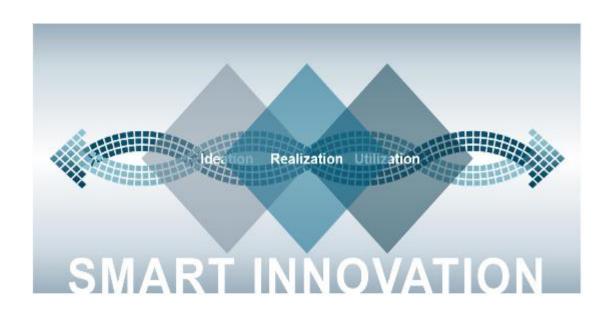
### SIEMENS 愿景:

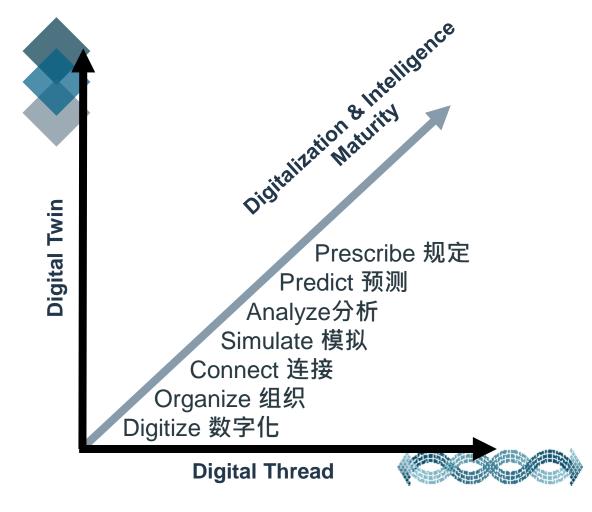
提供企业整体数字化、智能化软件解决方案-使新产品开发与实施更卓越。



# Combining intelligence and connectivity

结合智能和连接







#### 西门子聚焦:帮助公司实现卓越的新产品开发与实施





#### 提供具有竞争优势价值解决方案的半导体数字化平台

#### 半导体数字化平台价值解决方案

新产品开发与实 施项目管理和仪 表板

IMPROVE
NPI EXECUTION &
VISIBILITY

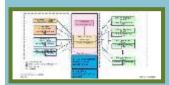
Provide a real-time objective dashboard for project / program status



IP管理与重用

IMPROVE PRODUCTIVITY

Enable Search,
Catalog,
Upload/Download,
Security and reuse
of Silicon IP



集成验证与确认

IMPROVE DESIGN YIELD

Enable end-to-end functional verification and physical test validation



设计规则手管理

IMPROVE WAFER
MANUFACTURABILITY

Ensure compliance of design to Fab manufacturability rules



芯片流片管理

IMPROVE DESIGN-TO-MASK QUALITY

Enable a clear signoff process from design to mask



设计与工程协作

EFFECTIVE SUPPLIER COLLABORATION

Enable
collaboration
between Fabless
and Foundry R&D
and Operation
teams



闭环质量管理

ENABLE CONTINUOUS IMPROVEMENT

Provide PLM-MES
Integrated solution
for closed loop
quality
management

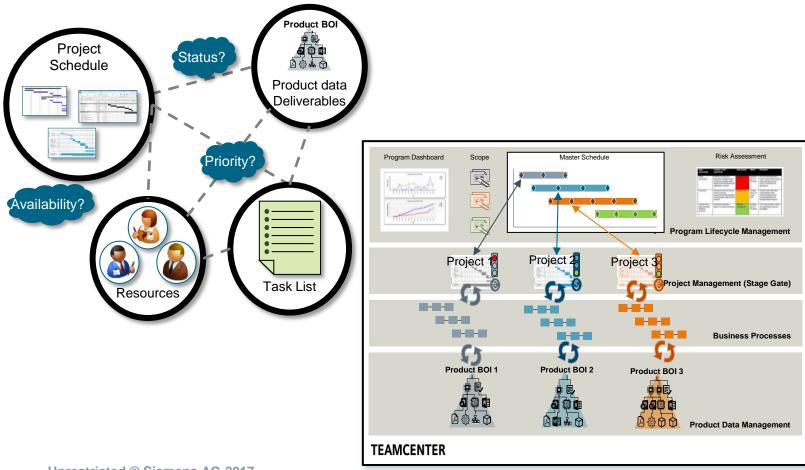


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#### 新产品开发与引进项目管理和仪表板



The Digitalization Platform provides an integrated solution for program, project, process and product data management.



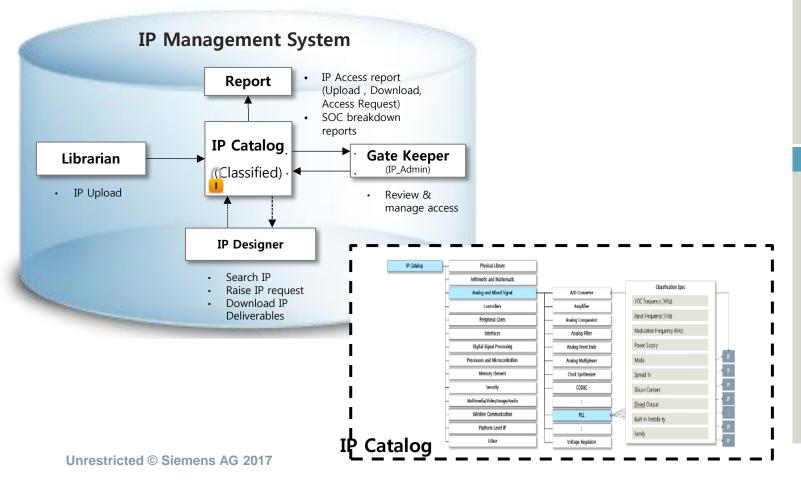
#### Challenges

- Inconsistent practices for project management across the organization
- **Time consuming** reporting and status update activities.
- No program view.
- Project Schedule / Tasks isolated from Document and Product Data Management applications
- Ad hoc communication

- Master Schedule View
- Program Dashboards
- Risks Management
- Resources Management
- Embedded Gantt Chart
- Timesheet, Baseline, Notification
- Workflows synchronized with project tasks
- Project deliverables based on preassigned templates

#### IP管理与重用

The Digitalization Platform provides a global IP repository, enabling IP Protection on 4 dimensions: Group/Role/User, Project, IP License and DRM.



#### Challenges

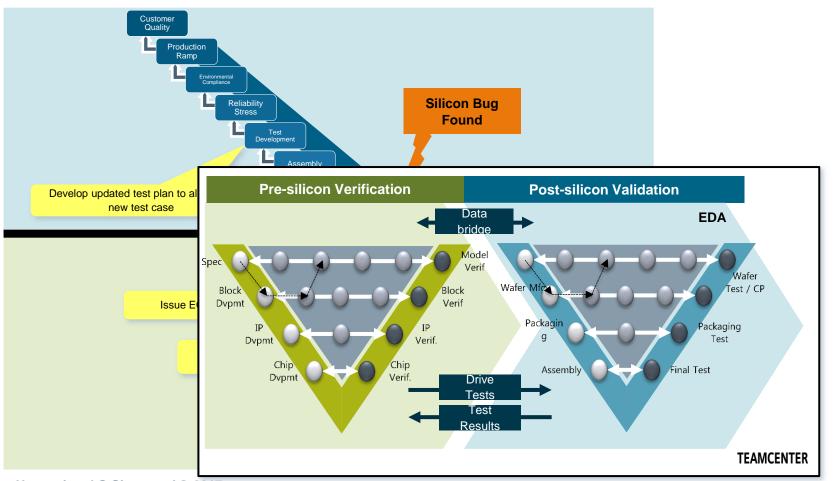
- Access to IP data is needed from many different internal and external roles located in different places.
- Access control is critical to preserve IP knowledge
- IP data is authored with various EDA tools, managed in multiple repositories
- IP catalog classification is complex

- IP Registration
- Designers can Request Access to some or all Deliverables for an IP Design
- Gatekeeper review request and provide Access Control
- If the Designer receives access, he can access deliverables and download to local workstation. (Data Share Manger)
- Audit trails show who received access and downloaded IP. (IP Data Cube)
- IP usage can be traced (Where Used)

#### 集成验证与确认



The Digitalization Platform supports the end-to-end process for SoC/SoC-BLOCK/IP Verification & Validation processes, and bridges the gap between Pre-silicon verification and Post-silicone validation.



#### Challenges

- Any ECO change has multiple impacts up and down the value chain.
- Verification, Validation & ECO change activities happen multiple time at multiple points of the process
- Verification and Validation processes are traditionally disconnected, with inefficient coverage, observability, data exchange, communication and information traceability

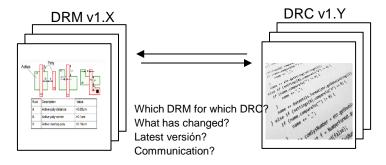
- Integrated data bridge between pre-silicon verification and post-silicon validation
- Integrated PLM , ALM, DevOps with EDA for continuing integration and delivery



#### 设计规则手管理

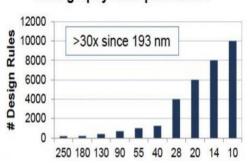
The Digitalization Platform provides rich capabilities to enable electronic DRM.

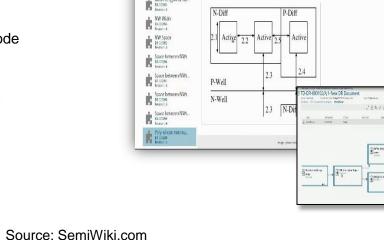
Validation Problem between Process/DRM/DRC and impact on Design



Complexity of DRC deck vs. Process node

#### Lithography: Complex Rules





#### Challenges

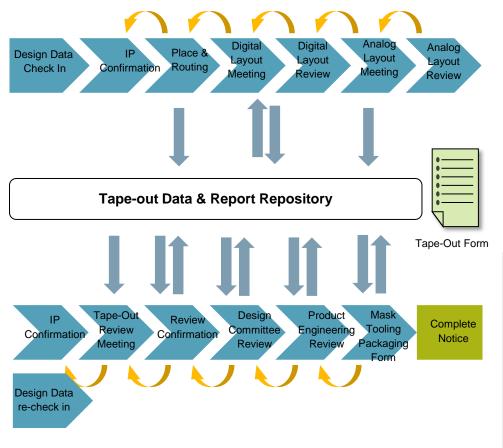
- DRM specification and the DRC runset are separated in time and space with many revisions over the lifetime of a chip
- Single mistake in the design flow from DRM to DRC can be fatal
- One DRM is the source of multiple DRC runsets but development and maintenance of every new DRC runset is expensive and introduces both risk and delays

#### **Capabilities**

- Import Design Rules (Word/Excel)
- Intuitive web based editor
- Manage Rich content
- Manage Design Rules Revisions
- Manage Workflows & Assignments
- Compare Design Rules
- Check List Management: Pool Management,
   Configurable list, Results management

#### 芯片流片管理

The Digitalization Platform drives the Tape-out release process by managing deliverables, checklists and workflows.



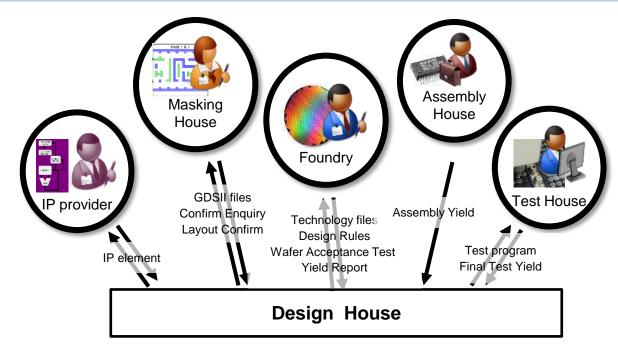


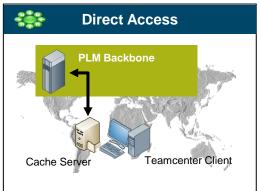
#### Challenges

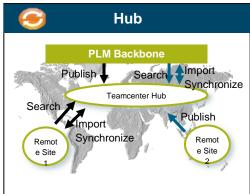
- Tape-out process involves many different internal and external stakeholders
- Tape-out process is complex, with many steps and branches
- Every step consume and generate data
- The information required to perform the Tape-out, is very diverse and evolving over time.
- Effective Tape-out process is key to avoid late error discovery, and significant costs

- Preconfigured workflows supporting the business process
- Tape-Out specific data model to efficiently managed the deliverables from the BOI.
- Flexible check lists to drive the review activities

#### 设计与工程协作









#### **Challenges**

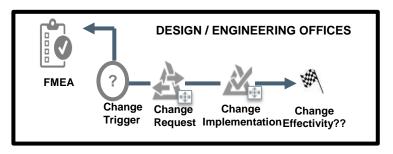
- Design and Engineering have to exchange information and data at multiple points of the NPI process
- Data exchange is bi-directional
- Tight Design Engineering collaboration is needed to avoid errors and therefore to reduce NPI time

#### **Capabilities**

- Asynchronous data exchange via web portal
- Synchronized data exchange via system integration
- Data exchange traceability and audit
- Immersive data sharing, enabling direct access with fine-grain security access control, and advanced File Management System (FMS)

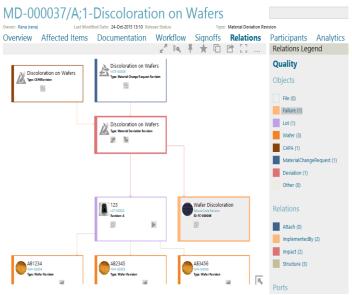
#### 闭环质量管理

The Digitalization Platform provides an integrated solution for Quality Management, including Non Conformance, CAPA, FMEA, Changes and audit.









#### Challenges

- Each plant has isolated deviation management processes, not connected to the Enterprise Change process.
- Lack of enterprise visibility and auditability of deviations and Non Conformances
- Change and deviation management processes are not related to the FMEA process

#### **Capabilities**

- FMEA analysis for system, product and process
- Flexible Change Process, including "fast track"
- Embedded Change Planning
- Change execution tacking, with effectivity per manufacturing site
- Deviation / Non Conformance retrieval
- Corrective and preventive actions management
- End-to-end audit

#### 进行战略收购 (近三年)



## ALM **Polarion Acquisition** PLM – ALM integration Continuous Delivery TEAMCENTER Physical State States and a street of the states and the states are states and the states are states and the states are states are states are states and the states are states a

# MES CAMSTAR **Camstar Acquisition** PLM – MES Integration





2015 / 12 2014 / 12 2014 / 12 2016 / 11

#### 总结:

#### 提供数字化、智能化清楚的半导体行业方向蓝图与完整的解决方案



